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(54) **Title:** PILOT UNIT

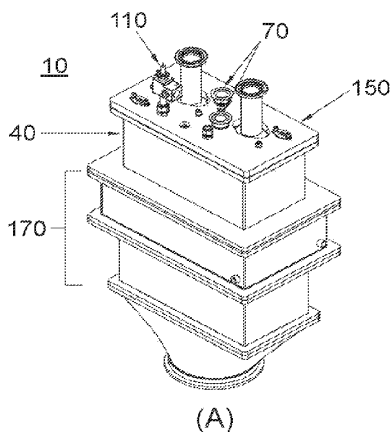


FIG. 1

(57) **Abstract:** A pilot unit for an abatement apparatus and a method are disclosed. The pilot unit is for an abatement apparatus configured to abate an effluent stream from a semiconductor processing tool, the pilot unit comprises: a housing retaining a foraminous pilot surface, the housing and foraminous pilot surface defining a plenum which is configured to convey fuel and oxidant from a corresponding housing inlet and through that foraminous pilot surface; and an ignitor configured to ignite the fuel and oxidant when exiting the foraminous pilot surface. In this way, rather than having an ignition flame combusting from a nozzle, an ignition flame is provided across the foraminous pilot surface which provides for a more reliable ignition source for the abatement apparatus.

WO 2023/287644 A1